

Part A Introduction To Servicing

This part of the manual is divided into the sections listed below. These sections provide some general and advisory information on servicing procedures, a brief history of T800 programming software, and a list of Technical Instructions pertaining to T830 Series equipment.

Section	Title	Page
1	General	1.1
1.1	Caution: CMOS Devices	1.1
1.2	Caution: Aerial Load	1.2
1.3	Caution: Beryllium Oxide & Power Transistors	1.2
2	Mechanical	2.1
2.1	Pozidriv Recess Head Screws	2.1
2.2	Disassembly/Reassembly	2.1
2.2.1	Receivers/Exciters	2.1
2.2.2	Power Amplifiers	2.1
2.3	Cover Screw Torques	2.1
3	Component Replacement	3.1
3.1	Leaded Components	3.1
3.1.1	Desoldering Iron Method	3.1
3.1.2	Component Cutting Method	3.1
3.2	Surface Mount Devices	3.2
4	To Replace PA Transistors	4.1
5	To Remove The T838 PA PCB From The Heatsink	5.1
6	To Remove Cased Mica Capacitors	6.1
7	Software History	7.1
7.1	BASEPROG V1/PGM800 V2	7.1
7.2	PGM800 V2.01	7.1
7.3	PGM800 V2.21	7.2
8	Technical Instructions	8.1

Figure	Title	Page
4.1	Typical Transistor/Capacitor Spacing	4.1

